

EUDET prototype

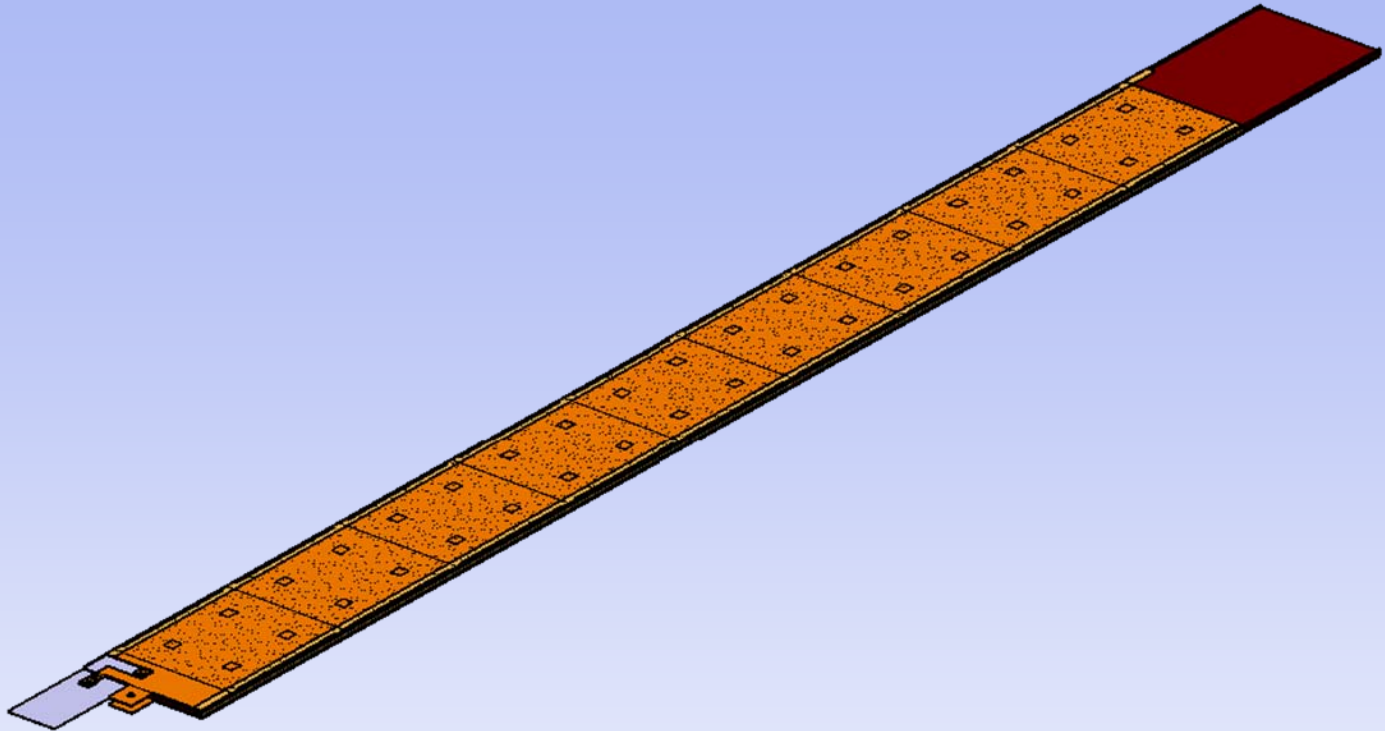
Thermal drain and plans for module assembly

- CAD model of demonstrator SLAB
- ASU/drain thermal junction
- Thermal test SLAB
- Physical short model
- Assembly and insertion equipments
- Facilities

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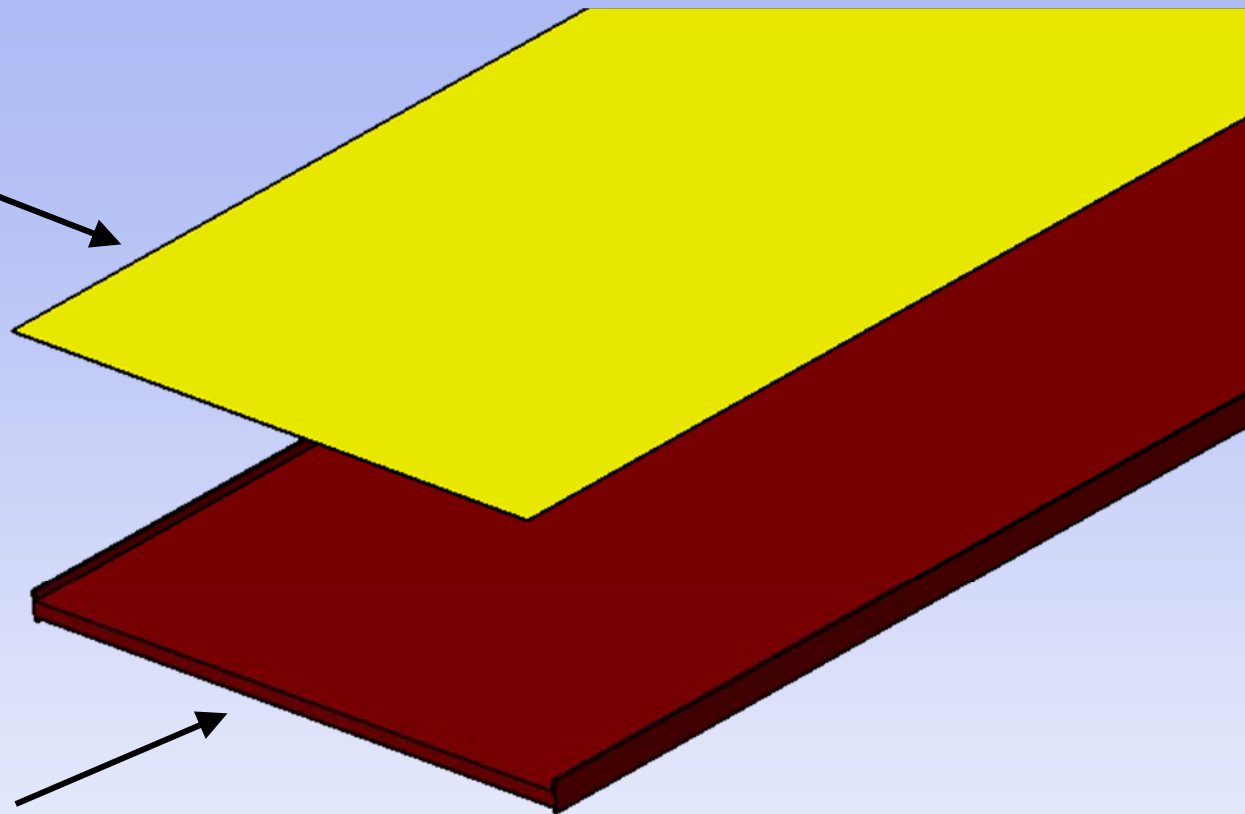


CAD model of Demonstrator Slab

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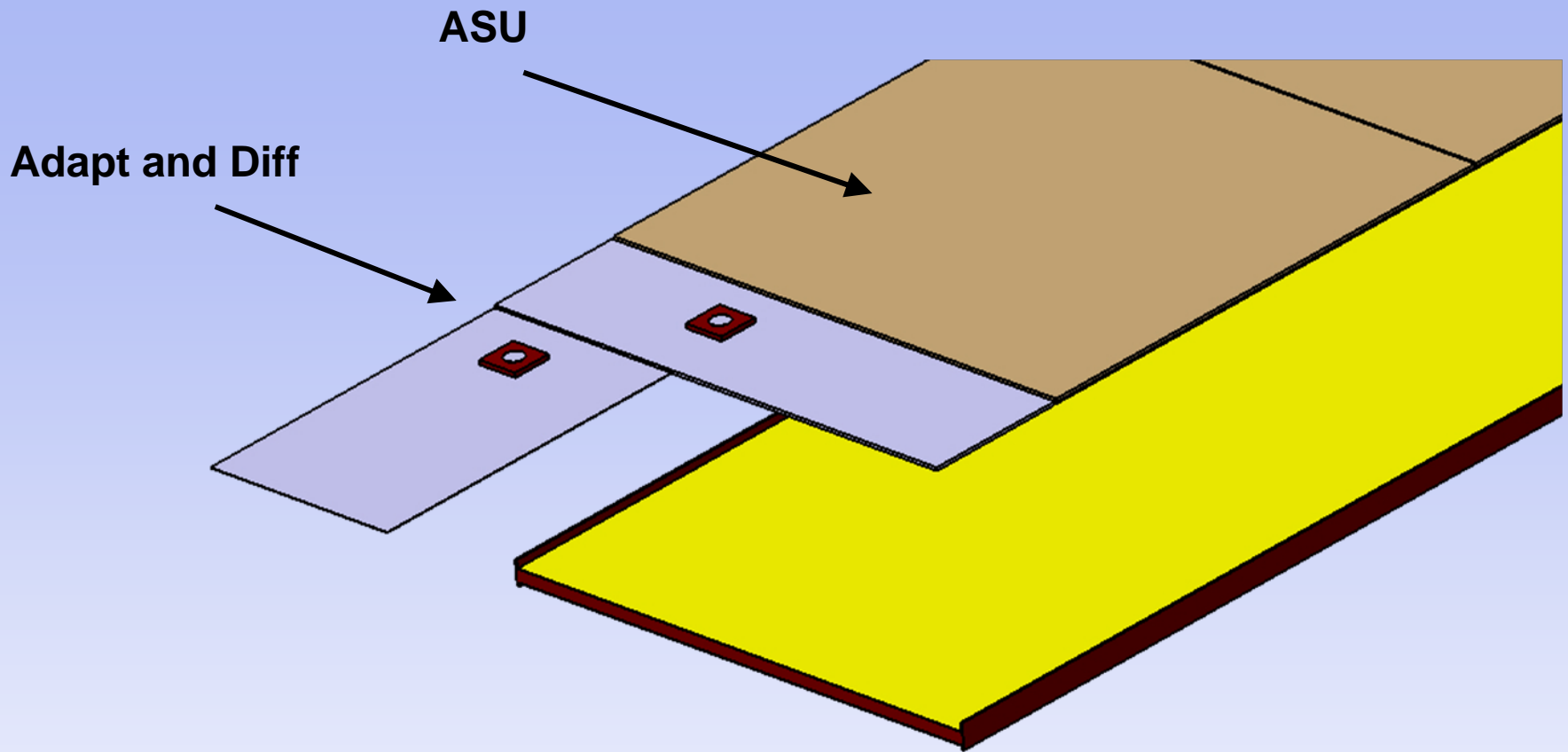
Kapton



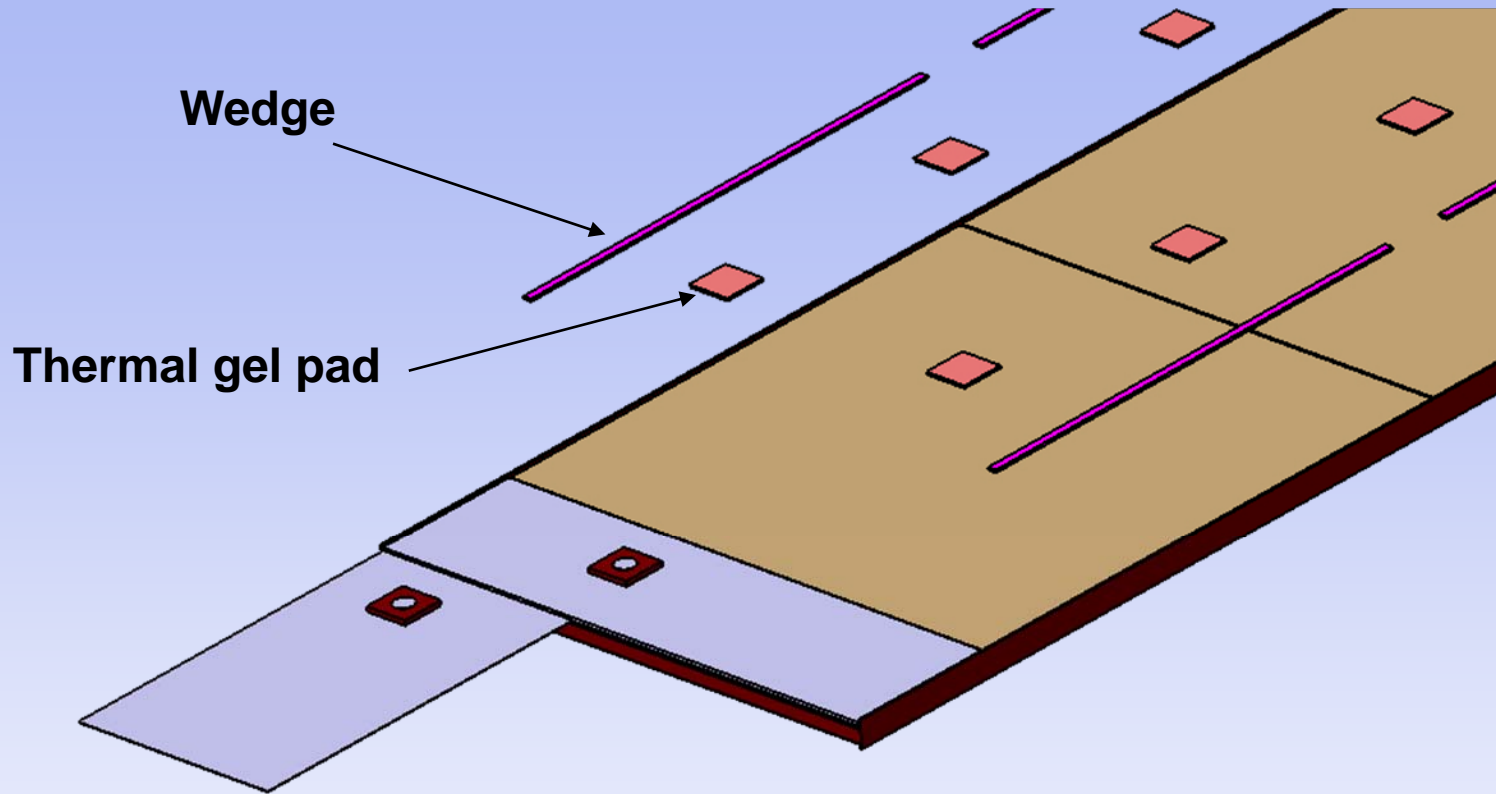
**H composite
with Tungsten**



Kapton are glue on H



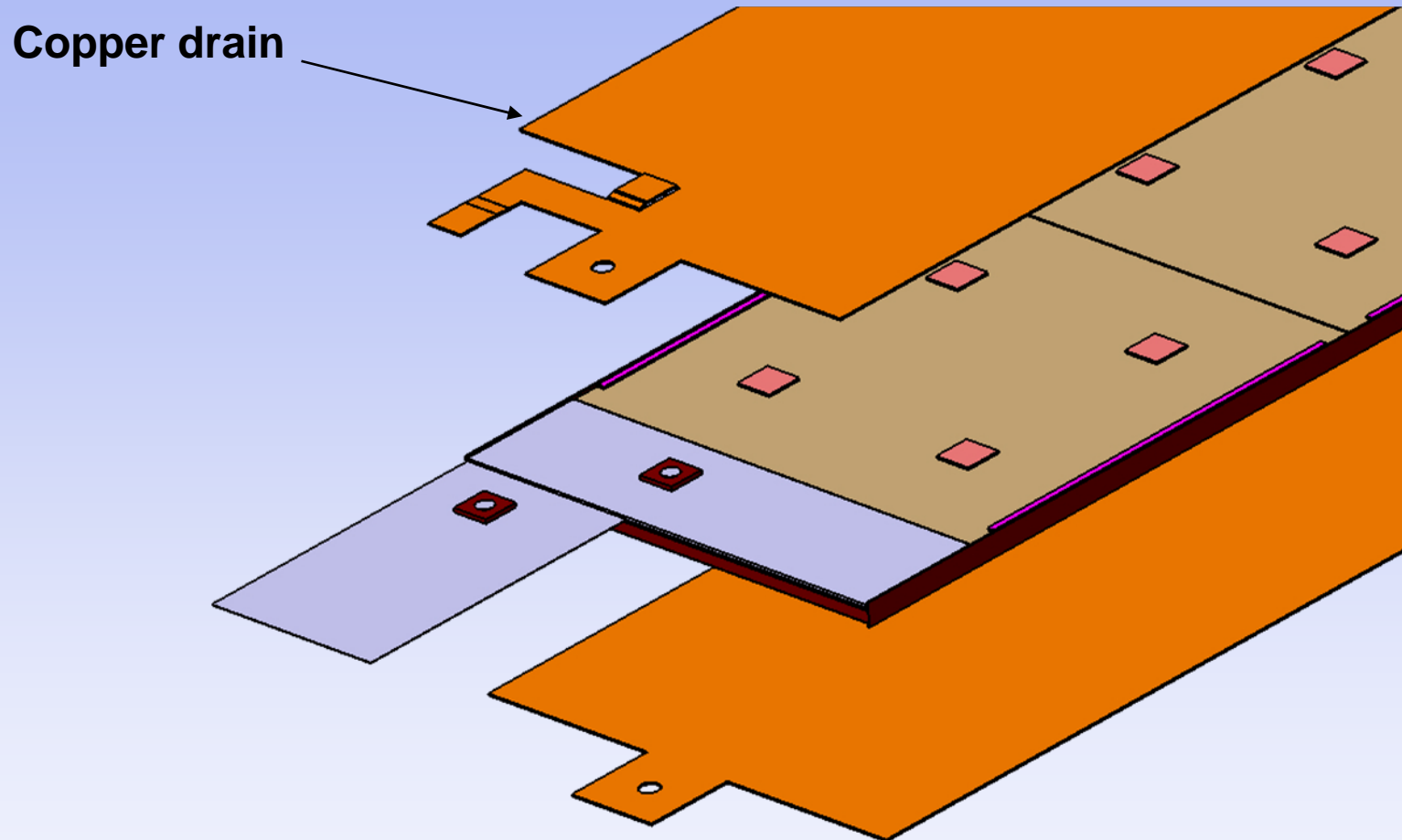
For EUDET : Wafer glue on Kapton for electrical junction



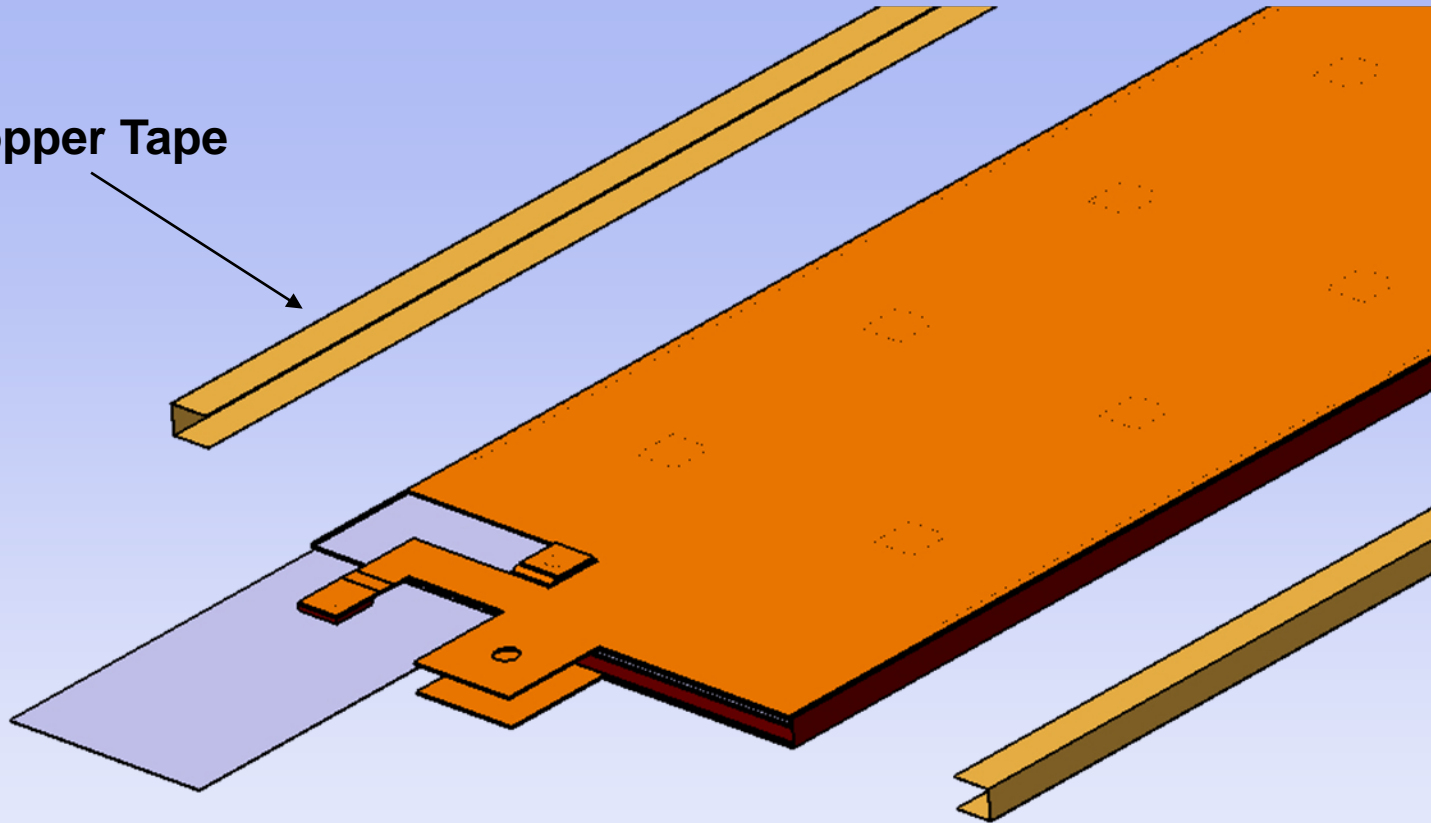
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Drains are keep flat by an equipement



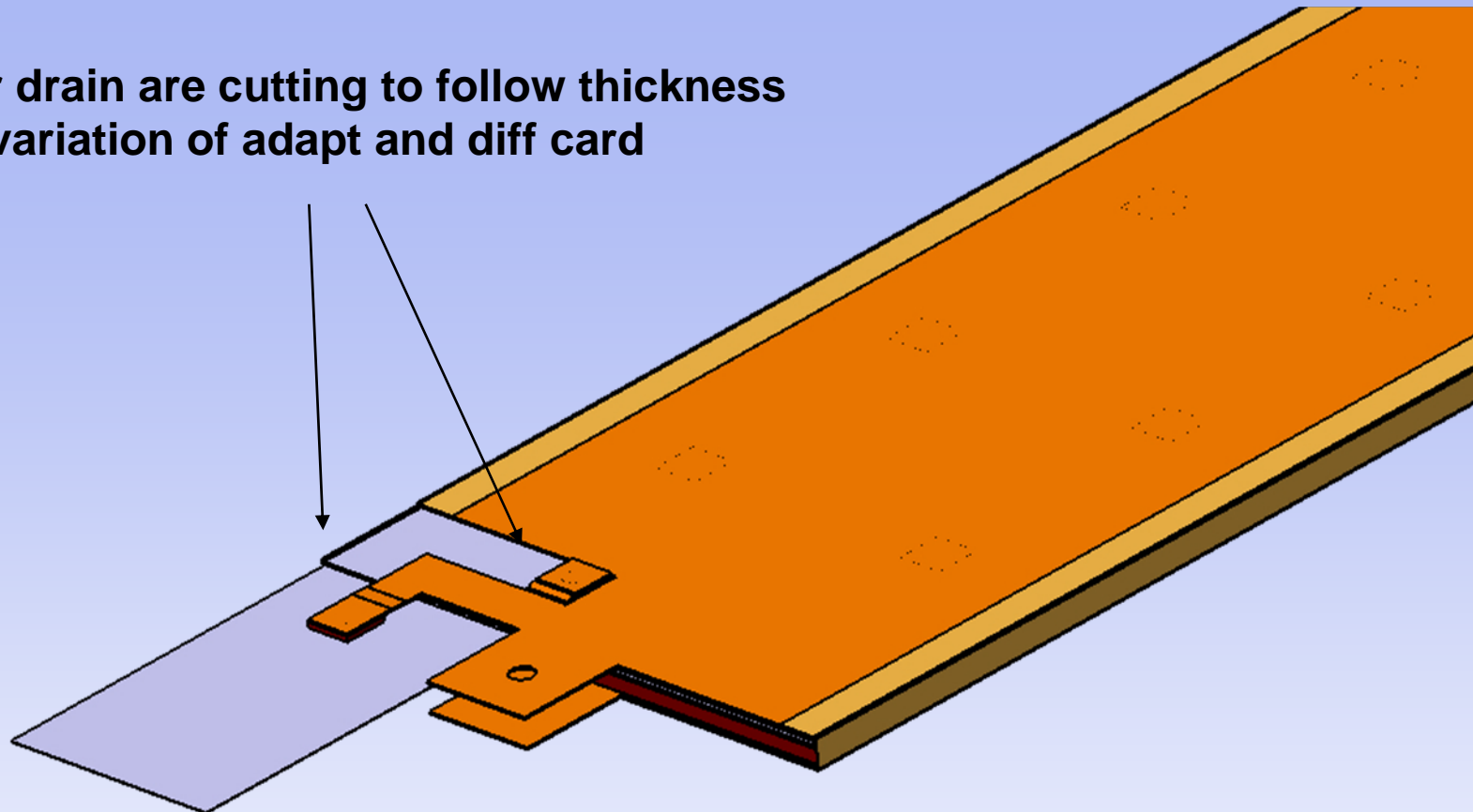
Copper Tape



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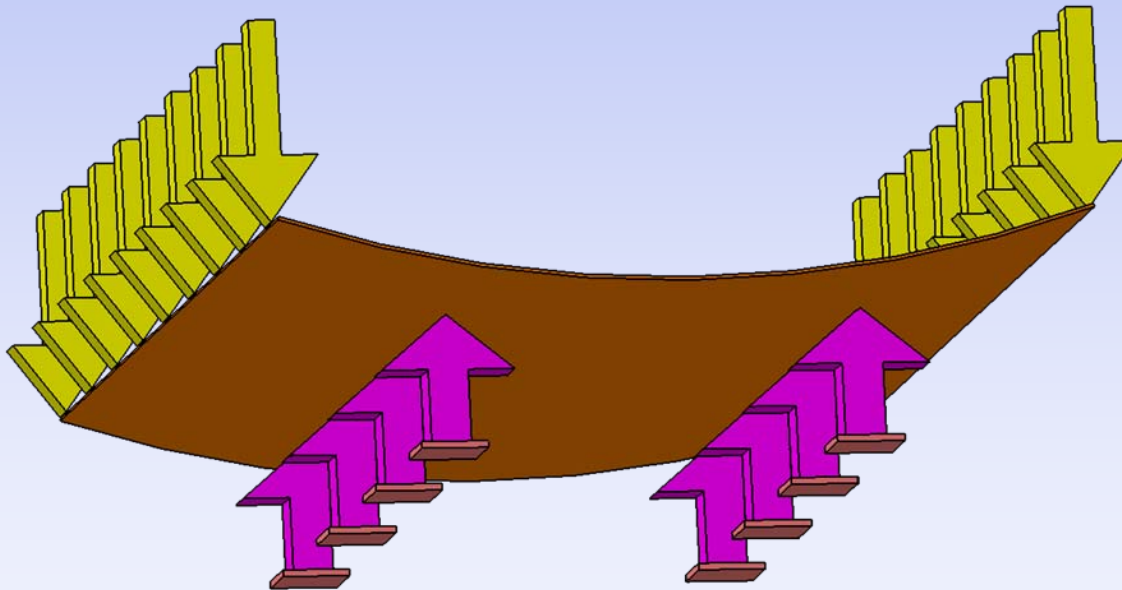
Copper drain are cutting to follow thickness variation of adapt and diff card

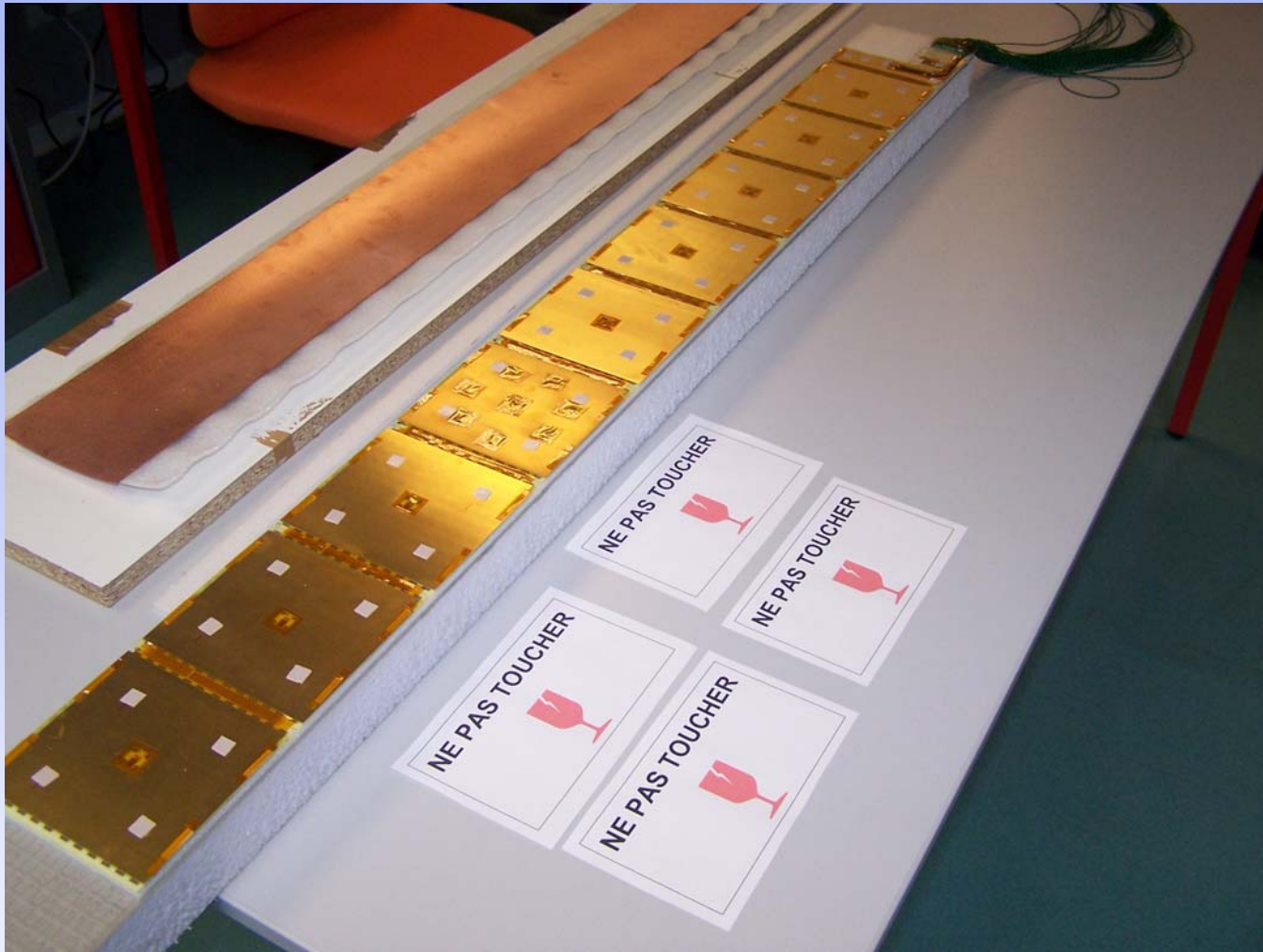


Tape effort



Reaction load of thermal gel pads

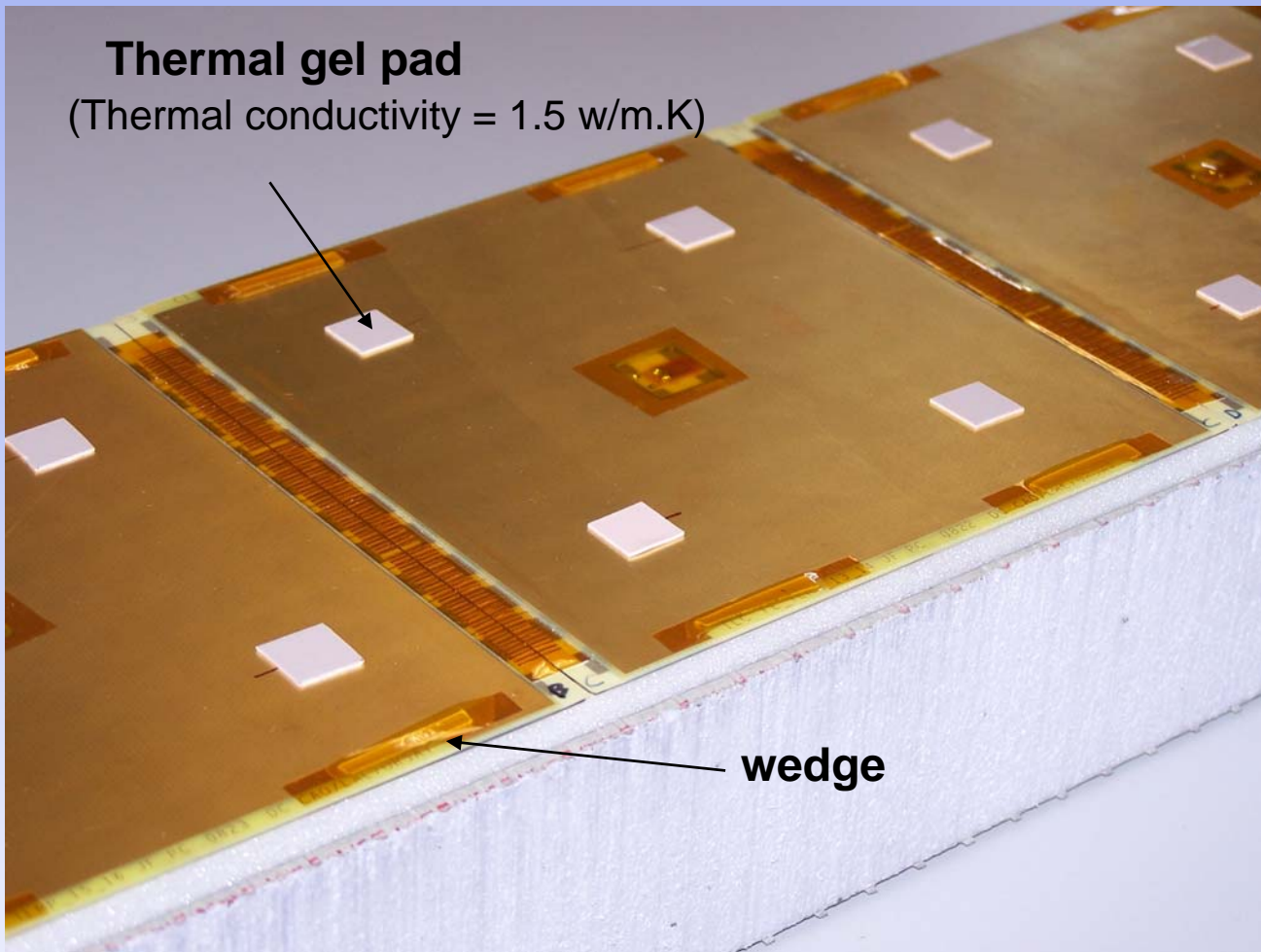




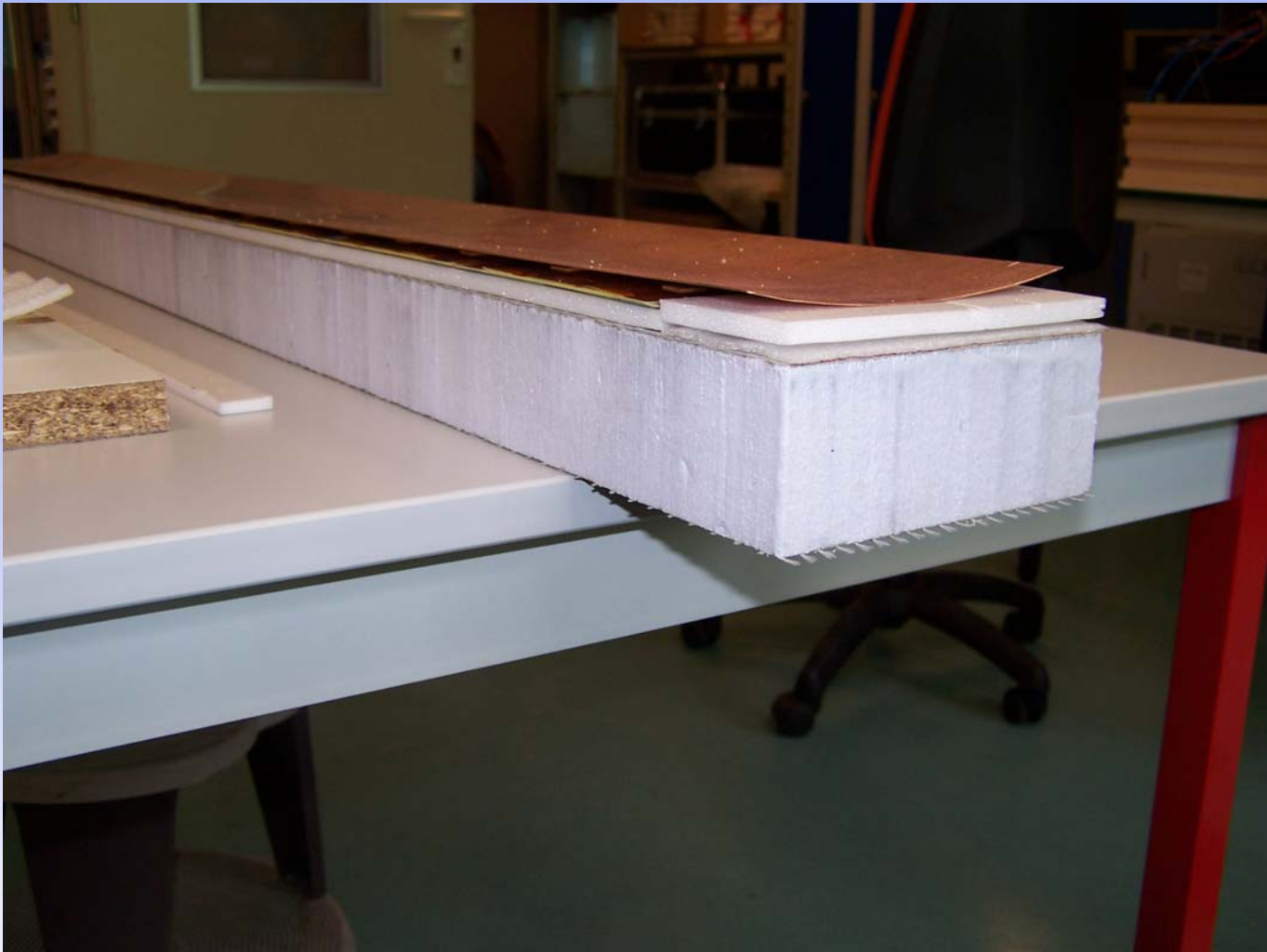
Ensemble demo ASU and curve copper drain

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Thermal gel pad and wedges on ASU



Thermal Slab before drain clamping

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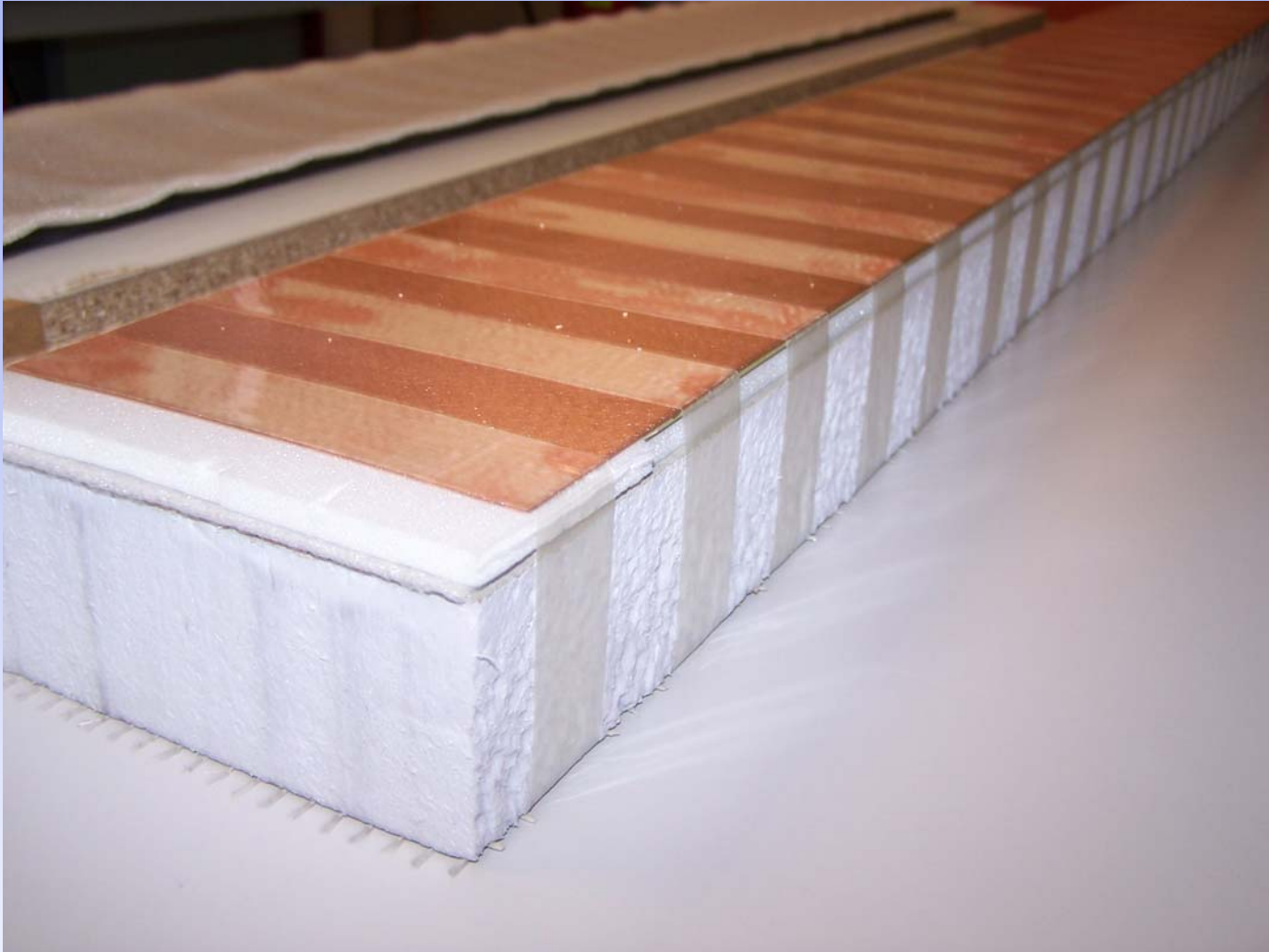
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Thermal Slab clamping

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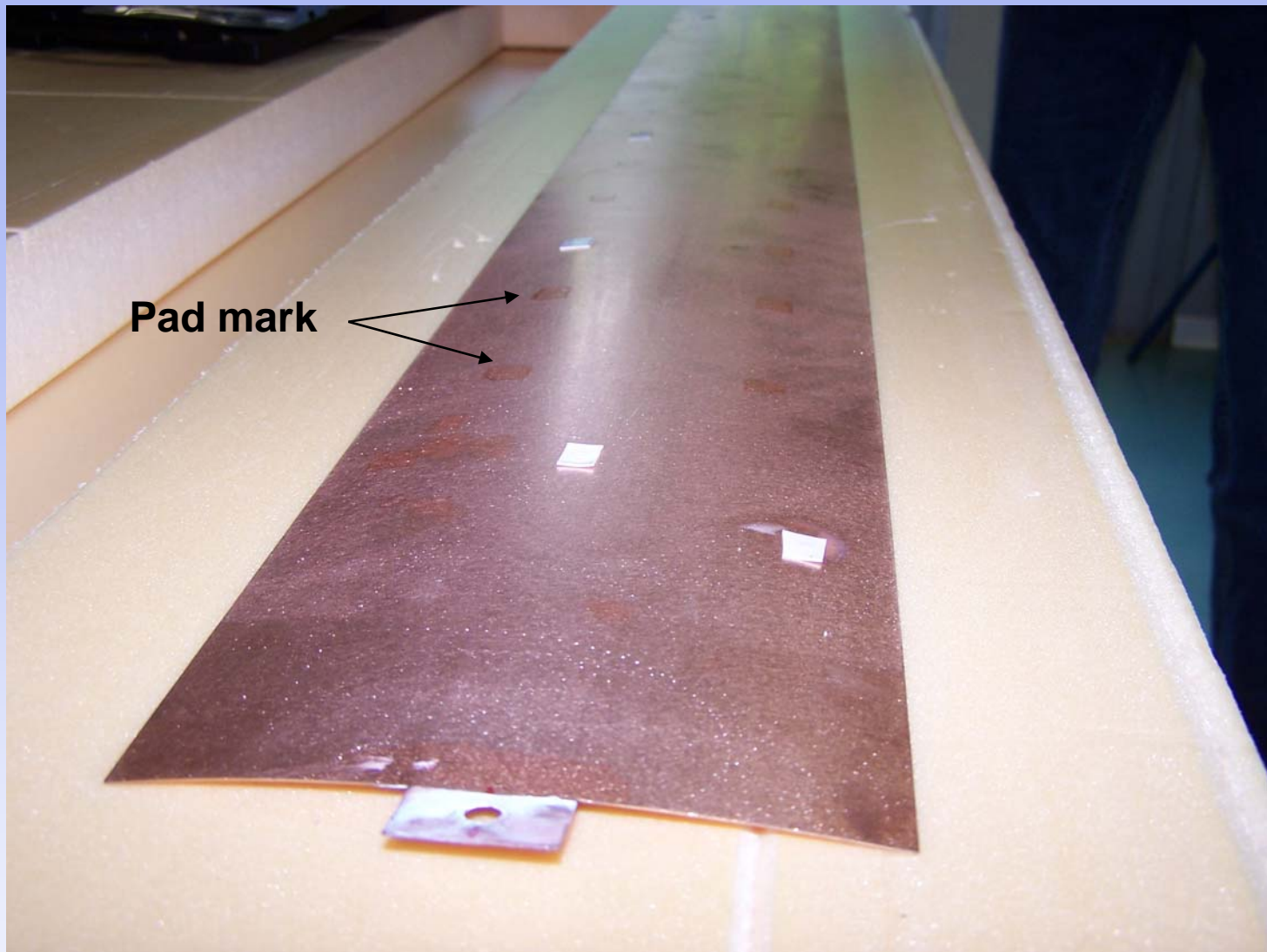
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Clamped thermal Slab

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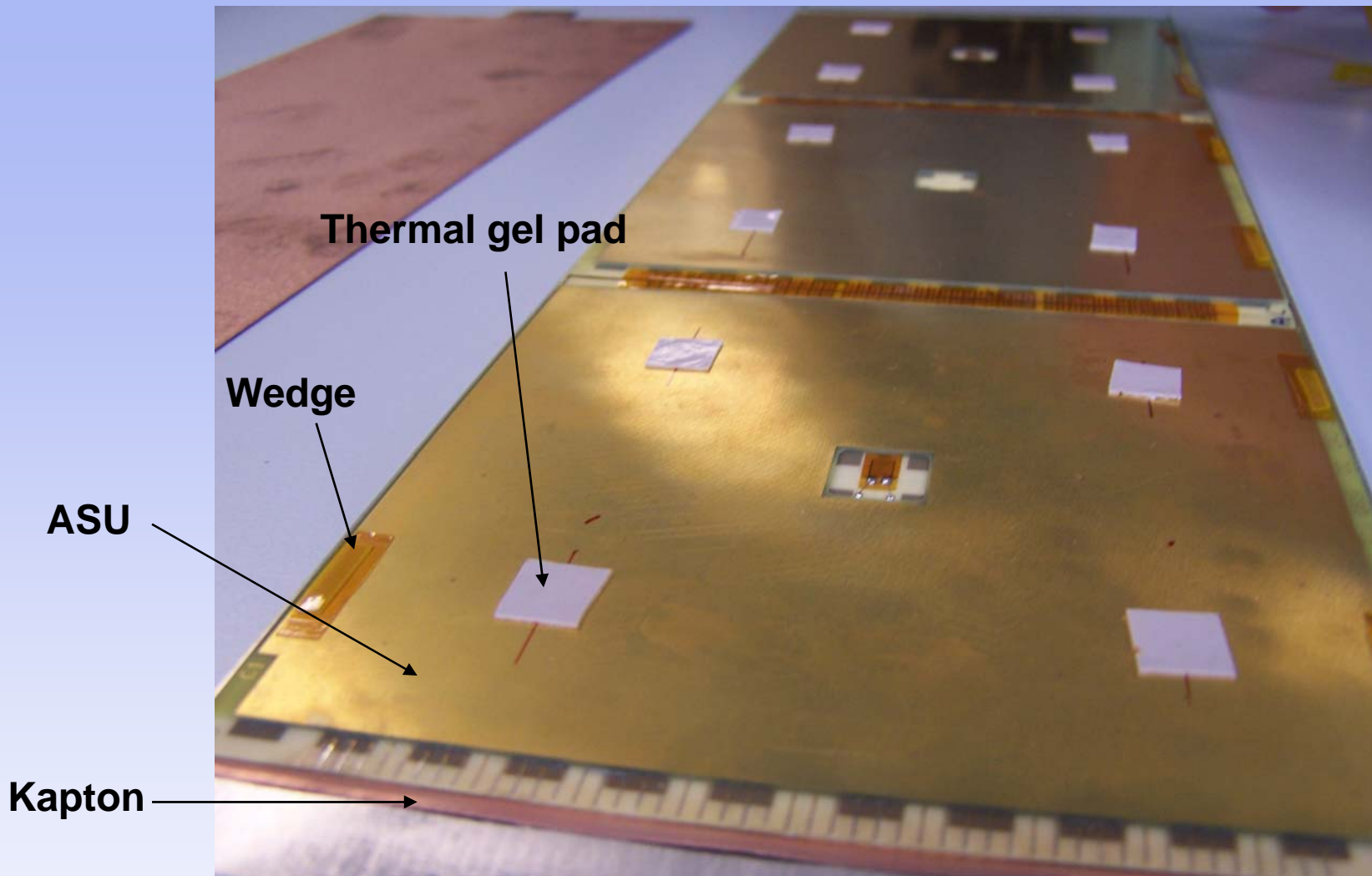
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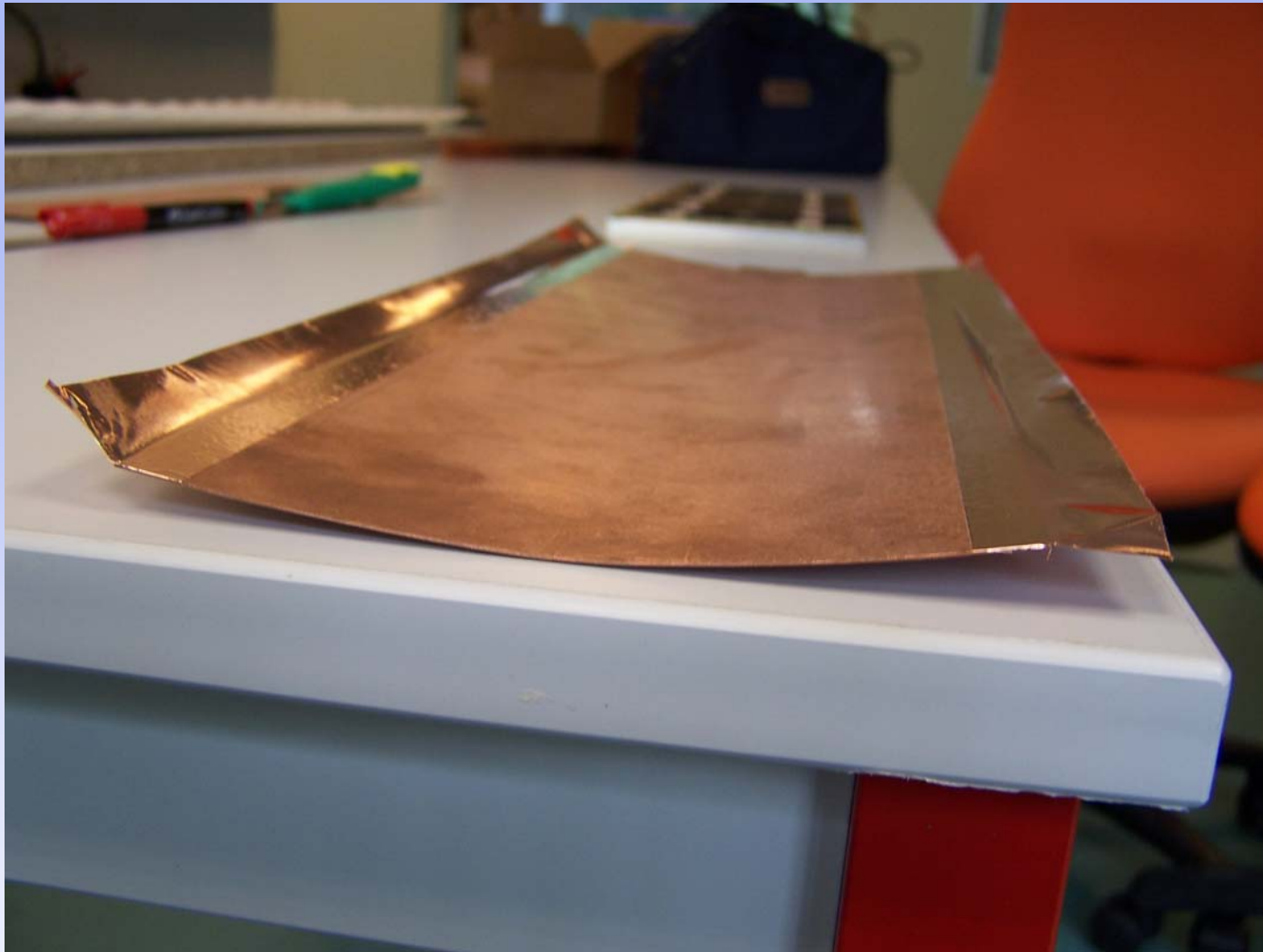
Pad mark on drain after disassembly of Slab

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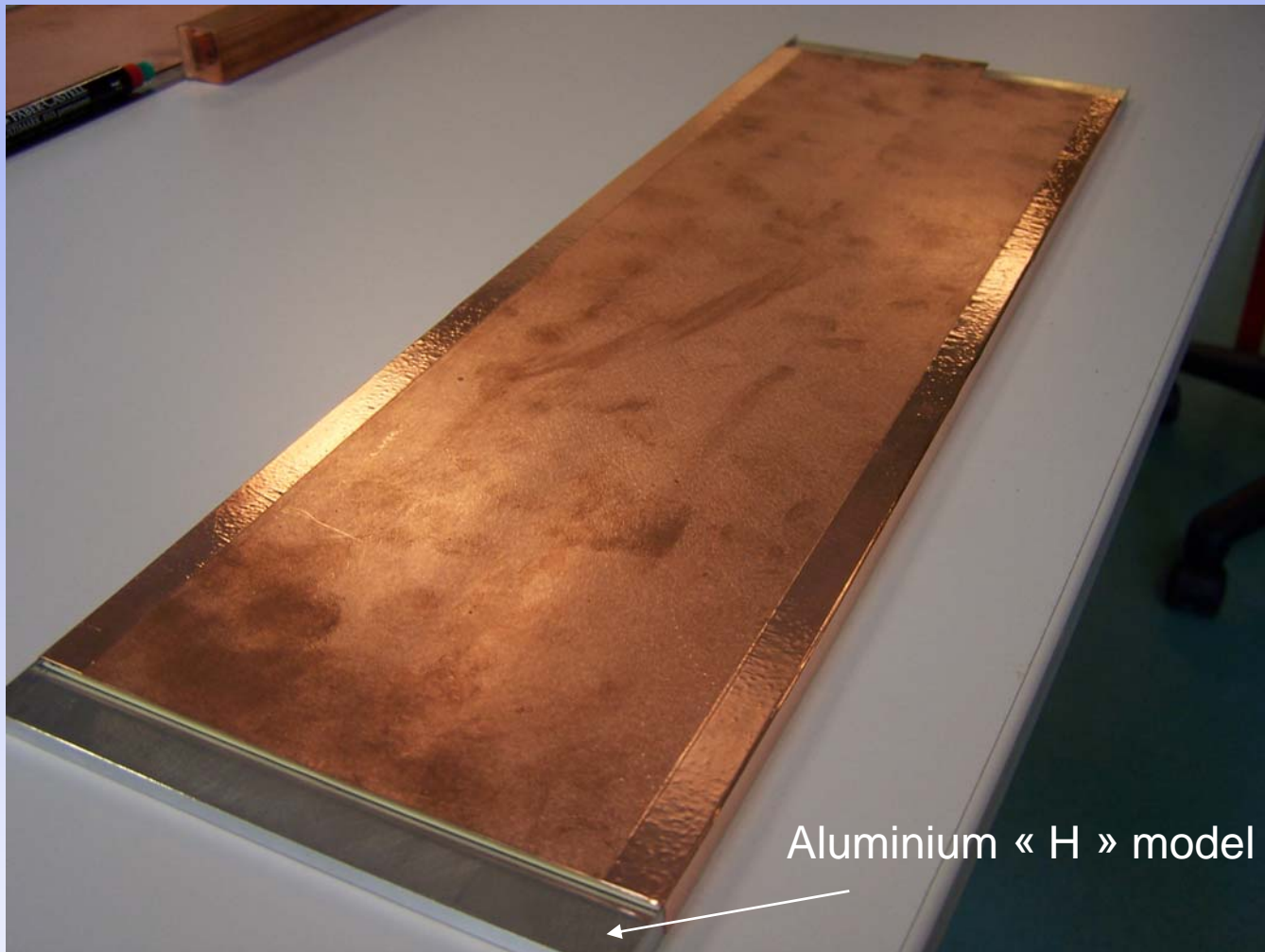
Kapton, demo ASU, thermal pads and wedges on model



Curve copper drain with copper tape

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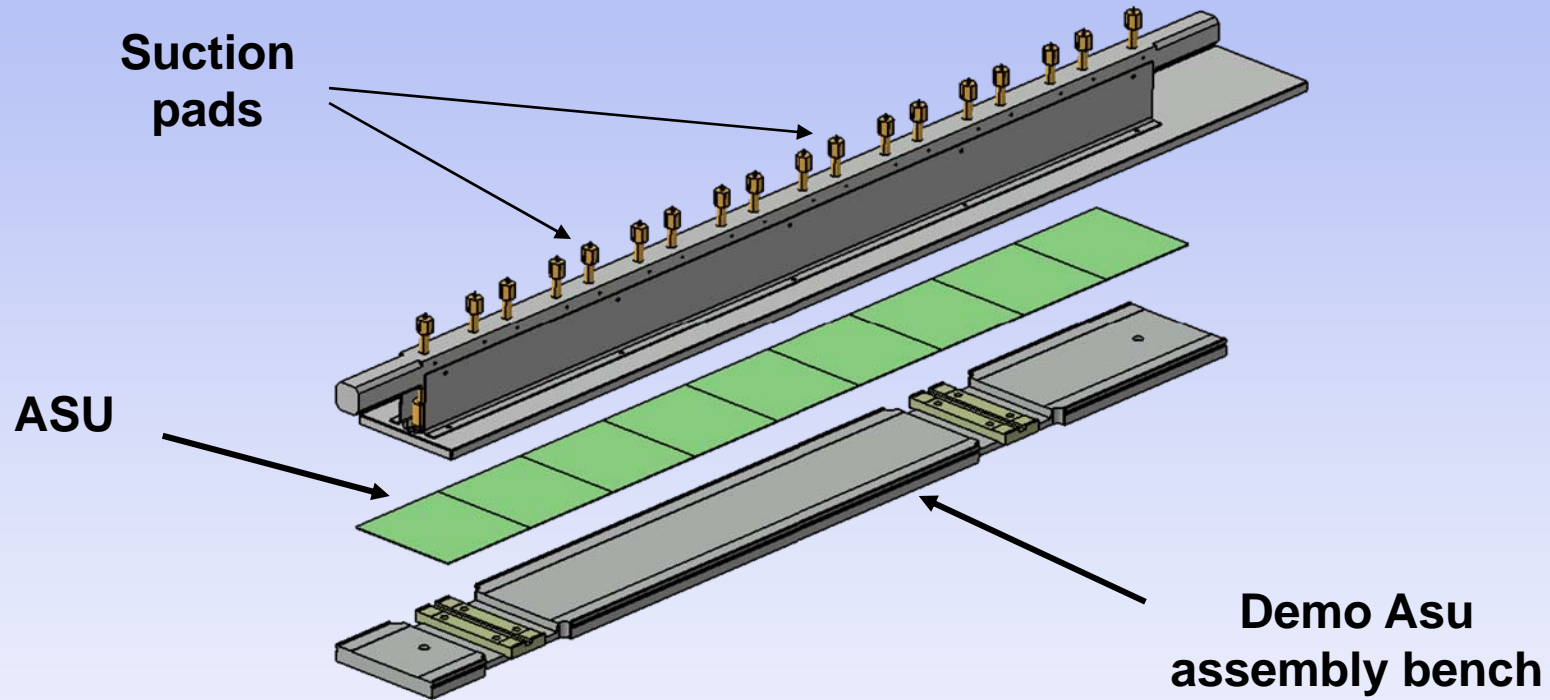


Physical short demonstrator Slab model

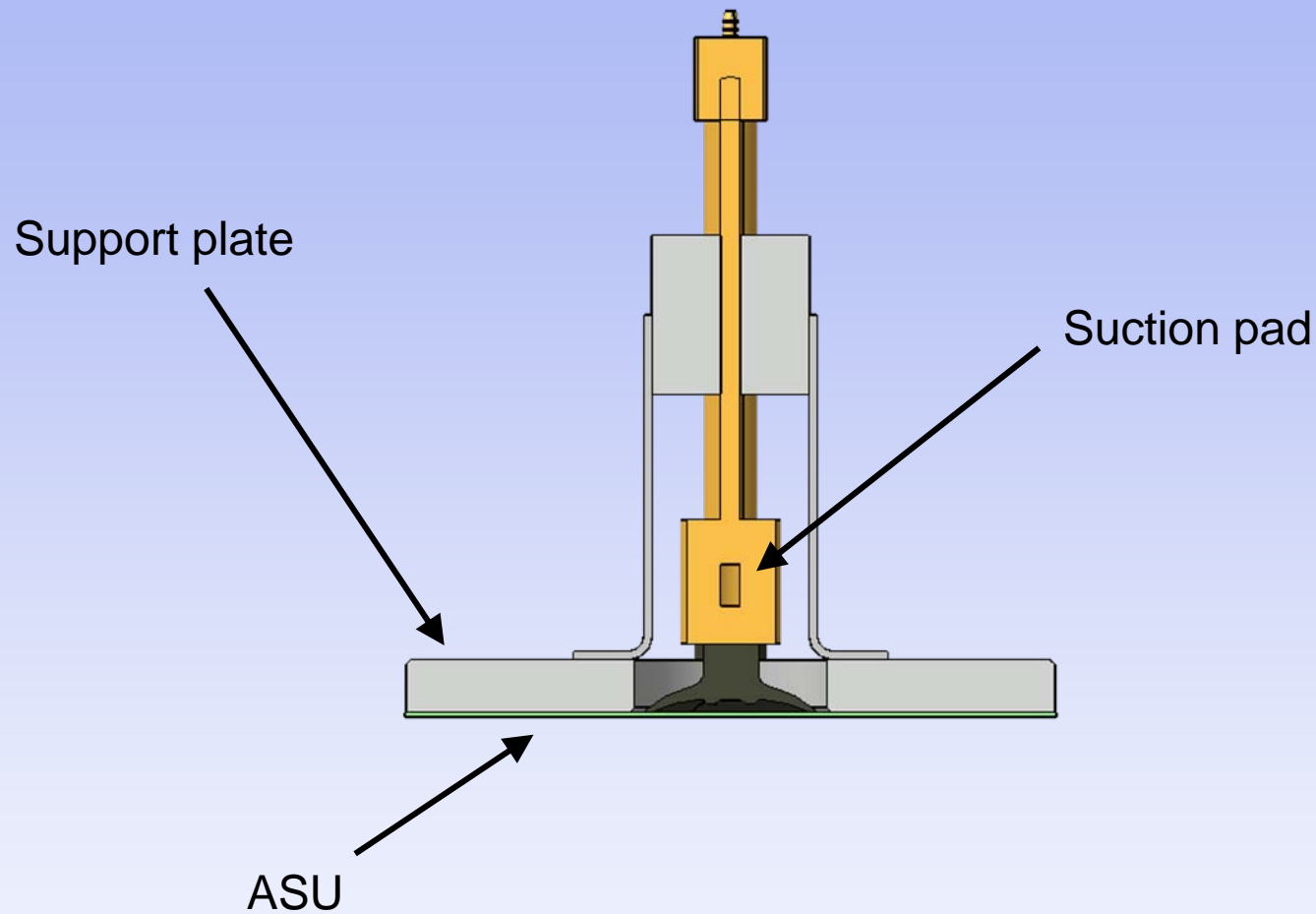
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Equipements



Suction pads manipulation equipement for ASU ensemble



Suction pads manipulation equipement for ASU ensemble

Under study

- **Curve copper drain in flate keeping position manipulator.**
- **Tape fitter.**
- **Eudet ASU assembly bench.**
- **Optimized curve of copper drain.**
- **Module insertion equipement.**
- **Conductive glue deposit equipement (Wafer/HT Kapton)**
- **Facilities**
 - **EUDET grey assembly room**
 - **Storage and transport box**
 - **Cosmic bench**

Demo Slab expected end of june